	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
1752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					als and Mfg Information					
upplier	· Information														
Company name* Compan				ompany unique ID			Unique ID Authority					Response Date*			
onsemi												2024-05-21			
Contact Name			Title - Contact]	Phone - Contact*				Email - Contact*				
Product-E	Env-Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
uthorized	d Representative*		Title - Representative]	Phone - Representative*				Email - Representative*				
roduct-E	Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
	Requester Item Number Mfr Item Nu FAN7711N		Number Mfr Item Name			·	Effective Date	te Version Manufacturing Site		v	Veight*	UOM	Unit Type		
			1N	Electronic Ballast IC			2024-05-21 TAD			478.247		mg	Each		
Ianufao	cturing Proccess Informa	tion					•					<u>,</u>			
	Terminal Plating / Grid Array Material		Ferminal Base Alloy J-STD-020 M		L Rating	Peak Process Body Temperat		ure Max Time at Peak Temp		Temperatu	ire Numb	per of Reflow Cyc	les		
Matte Tin (Sn) - annealed		CU Alloy NA			0 C		30		second	ls 3					
omments															
or more i	information regarding material	composition	please refer to	o page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU												
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and co for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of							
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	on above	Supplier Acceptance	* Accepted								
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all							
Exemption List Version	EL-2011/534/EU											
Declaration Signature												
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the							
Supplier Digital Signature Ra	stislav Drska	Le										

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	1.6	mg	Supplier	Silicon (Si)	7440-21-3		1.6	mg
Die Attach	3.0	mg		Epoxy resin	proprietary data		0.3	mg
			Supplier	Silver (Ag)	7440-22-4		2.4	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.3	mg
Lead Frame	137.787	mg	Supplier	Silver (Ag)	7440-22-4		1.3503	mg
			Supplier	Zinc (Zn)	7440-66-6		0.1653	mg
			Supplier	Iron (Fe)	7439-89-6		3.238	mg
			Supplier	Copper (Cu)	7440-50-8		133.0058	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0276	mg
Mold Compound-Black	320.81	mg		Epoxy resin	proprietary data		22.4567	mg
			Supplier	Phenolic Resin	Proprietary Data		8.0203	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		24.0608	mg
			Supplier	Carbon Black (C)	1333-86-4		1.604	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		256.648	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		8.0202	mg
Plating	9.05	mg	Supplier	Tin (Sn)	7440-31-5		9.05	mg
Wire Bond - Au	6.0	mg	Supplier	Gold (Au)	7440-57-5		6	mg

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).